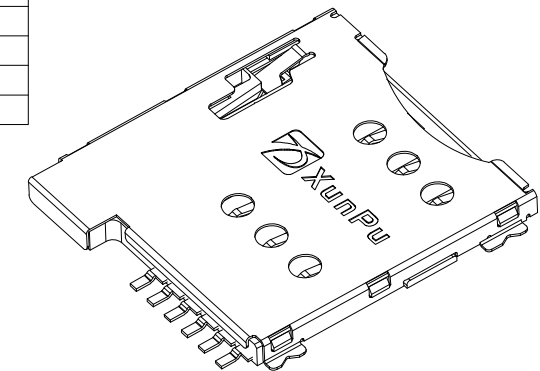


MATERIAL:
INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL 94V-0
CONTACT: COPPER ALLOY
SHELL: SUS

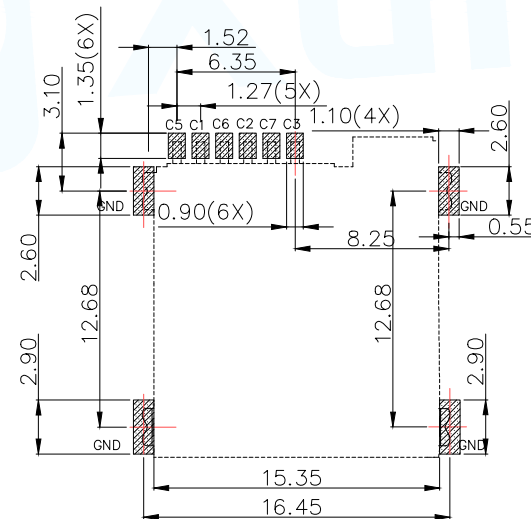
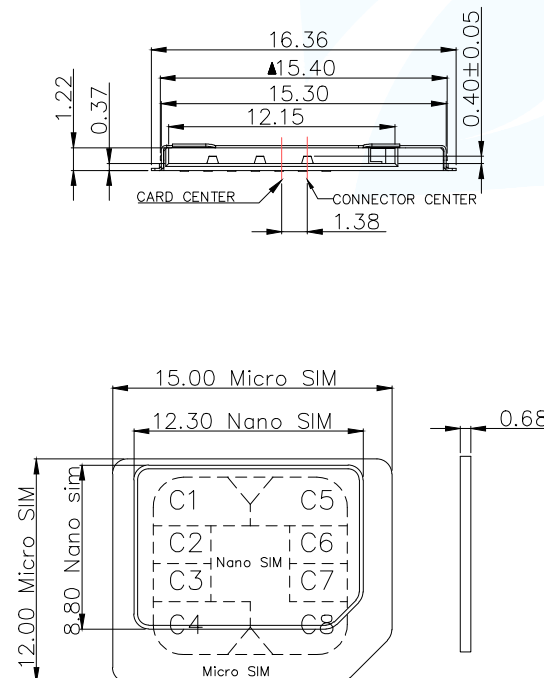
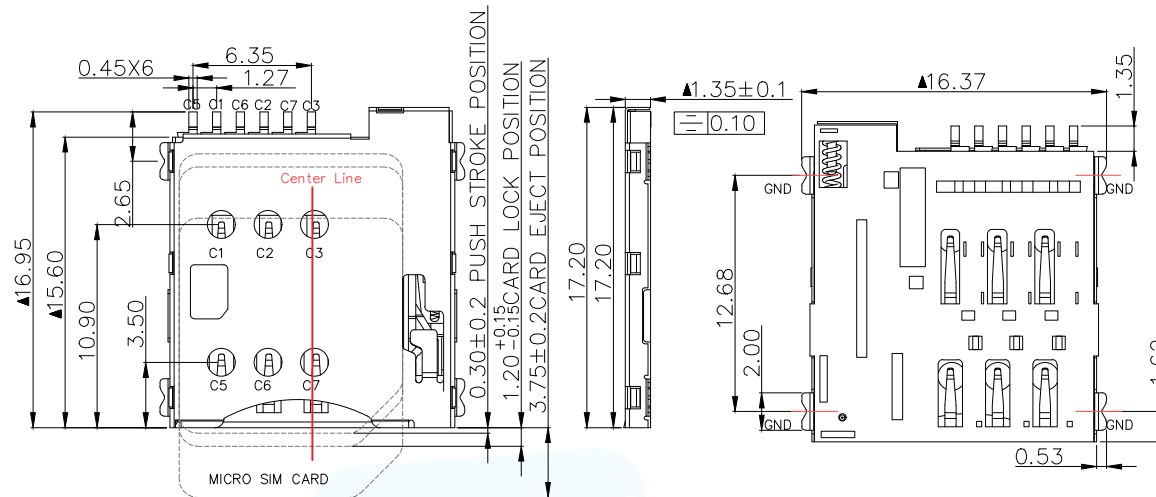
PLATING:
CONTACT: PLATED 50U" NI OVER ALL CONTACT AU 1U
SHELL: PLATED 50U" NI OVERALL
PLATED 1U" AU SELECTIVE CONTACT AREA

ELECTRICAL:
CURRENT RATING: 0.5MA
VOLTAGE RATING: 5V AC/DC
AMBIENT TEMPERATURE RANGE: $-20^{\circ}\text{C} \sim +60^{\circ}\text{C}$
STORAGE TEMPERATURE RANGE: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$
AMBIENT HUMIDITY RANGE: 95% R.H. MAX.
CONTACT RESISTANCE: 100M MAX Ω
INSULATION RESISTANCE: 1000M MIN./500VDC Ω
REFLOW PEAK TEMP: 260 $^{\circ}\text{C}$
MATING CYCLES: 5000MIN INSERTIONS

MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: MICRO SIM CARD PUSH PUSH 6PIN H1.35
			PAR SMC-202-6
DECIMALS:	ANGLES: $\pm 1^{\circ}$		DWN YAO
X.X: ± 0.15			CHKD
X.XX: ± 0.10		SCALE 1:1 UNIT: MM	
X.XXX: ± 0.05		CUSTOMER COPY	
		SIZE: A4	SHEET: 1F1
			REV: A



PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05